

Electronic Patent Application Fee Transmittal

Application Number:	10507325
Filing Date:	10-Sep-2004
Title of Invention:	Method and apparatus for processing brittle material
First Named Inventor/Applicant Name:	Hideki Morita
Filer:	Lee Cheng/Maki Huffman
Attorney Docket Number:	APA-0216

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 2 months with \$0 paid	1252	1	490	490

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				490